

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 2237 | thermoelectric and wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/08 07:44 |
| L2 | 1144 | l1 and bond\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/08 09:42 |
| L4 | 4724 | thermoelectric and (ic or die or wafer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/08 10:55 |
| L5 | 800 | l4 and (bi or te or sb or pb or ag or ge or zn) and alloy | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/08 10:56 |
| L6 | 697 | l5 and heat | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/08 10:57 |